





(1,27 mm) .050"

**CLP SERIES** 

# PROFILE DUAL WIPE SOCKET

#### **SPECIFICATIONS**

For complete specifications and recommended PCB layouts see www.samtec.com?CLP

Insulator Material:

Black Liquid Crystal Polymer Contact Material: Phosphor Bronze

Plating: Sn or Au over

50μ" (1,27 μm) Ni Current Rating (CLP/FTSH): 3.3 A per pin

(1 pin powered per row) Voltage Rating: 240 VAC/340 VDC

**Operating Temp Range:** -55°C to +125°C Contact Resistance:

 $10~\text{m}\Omega$ Insertion Depth:

Top Entry = (1,40 mm) .055" minimum, Bottom Entry = (2,41 mm) .095" minimum plus board thickness DH Entry = (2,31 mm) .091" to (2.67 mm) .105" Insertion Force: (Single contact only) 3.8 oz (1,05 N) average Normal Force:

60 grams (0,59 N) average Withdrawal Force: (Single contact only)

Corporation (Gringle Contract Gring)

2 oz (0,56 N) average

Max Cycles:

100 with 10μ" (0,25 μm) Au

RoHS Compliant:

## Processing: Lead-Free Solderable:

SMT Lead Coplanarity: (0,10 mm) .004" max (02-35) (0,15 mm) .006" max (36-50)

### **RECOGNITIONS**

For complete scope of recognitions see www.samtec.com/quality



### ALSO AVAILABLE (MOQ Required)

- Single row
- · Other platings Contact Samtec.

Note: Some sizes, styles and options are non-standard, non-returnable.



